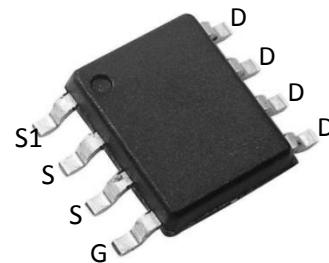


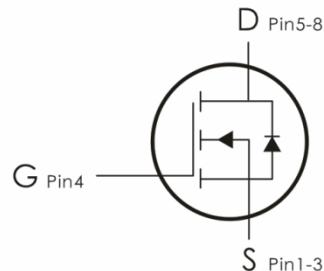
## Description:

This N-Channel MOSFET uses advanced trench technology and design to provide excellent  $R_{DS(on)}$  with low gate charge. It can be used in a wide variety of applications.



## Features:

- 1)  $V_{DS}=30V, I_D=18A, R_{DS(on)}<6m\Omega @ V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low  $R_{DS(on)}$ .
- 5) Excellent package for good heat dissipation.



## Absolute Maximum Ratings: ( $T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current- $T_A=25^\circ C$ <sup>1</sup>	18	A
	Continuous Drain Current- $T_A=100^\circ C$ <sup>1</sup>	10	
	Pulsed Drain Current	70	
$P_D$	Power Dissipation, $T_c=25^\circ C$ <sup>4</sup>	4	W
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	°C

## Thermal Characteristics:

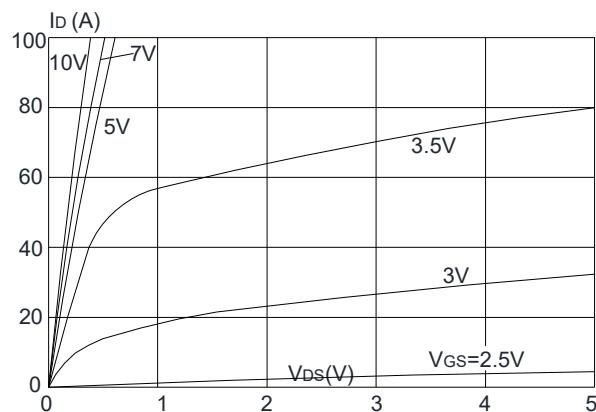
Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance,Junction to Case	50	°C/W

**Electrical Characteristics:** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

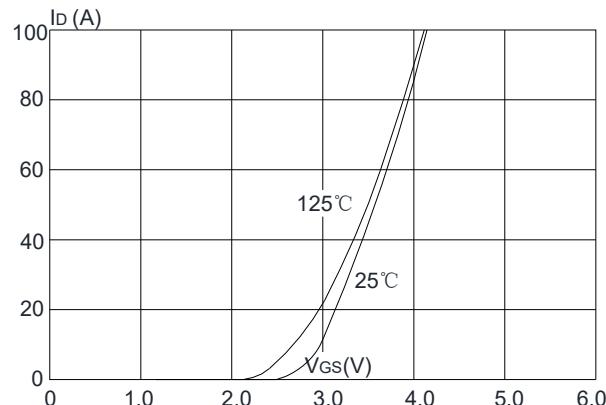
Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
<b><math>\text{BV}_{\text{DSS}}</math></b>	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250 \mu\text{A}$	30	---	---	V
<b><math>I_{\text{DSS}}</math></b>	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=30\text{V}$	---	---	1	$\mu\text{A}$
<b><math>I_{\text{GSS}}</math></b>	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{A}$	---	---	$\pm 100$	nA
<b>On Characteristics</b>						
<b><math>V_{\text{GS}(\text{th})}</math></b>	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250 \mu\text{A}$	1	1.5	2.5	V
<b><math>R_{\text{DS}(\text{ON})}</math></b>	Drain-Source On Resistance <sup>3</sup>	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=10\text{A}$	---	4.8	6	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=5\text{A}$	---	7.5	12	
<b>Dynamic Characteristics</b>						
<b><math>C_{\text{iss}}</math></b>	Input Capacitance	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	1614	---	pF
<b><math>C_{\text{oss}}</math></b>	Output Capacitance		---	245	---	
<b><math>C_{\text{rss}}</math></b>	Reverse Transfer Capacitance		---	215	---	
<b>Switching Characteristics</b>						
<b><math>t_{\text{d(on)}}</math></b>	Turn-On Delay Time	$V_{\text{DD}}=15\text{V}, I_{\text{D}}=30\text{A}, V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=3\Omega$	---	7.5	---	ns
<b><math>t_r</math></b>	Rise Time		---	14.5	---	ns
<b><math>t_{\text{d(off)}}</math></b>	Turn-Off Delay Time		---	35.2	---	ns
<b><math>t_f</math></b>	Fall Time		---	9.6	---	ns
<b><math>Q_g</math></b>	Total Gate Charge	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=15\text{V}, I_{\text{D}}=30\text{A}$	---	33.7	---	nC
<b><math>Q_{\text{gs}}</math></b>	Gate-Source Charge		---	8.5	---	nC
<b><math>Q_{\text{gd}}</math></b>	Gate-Drain "Miller" Charge		---	7.5	---	nC
<b>Drain-Source Diode Characteristics</b>						
<b><math>V_{\text{SD}}</math></b>	Source-Drain Diode Forward Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=30\text{A}$	---	---	1.2	V
<b><math>I_s</math></b>	Continuous Source Current	---	---	---	70	A
<b><math>I_{\text{sm}}</math></b>	Pulsed Source Current		---	---	280	A

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
  2. EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{DD}=15\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $R_G=25\Omega$ ,  $L=0.5\text{mH}$ ,  $I_{AS}=15\text{A}$
  3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$

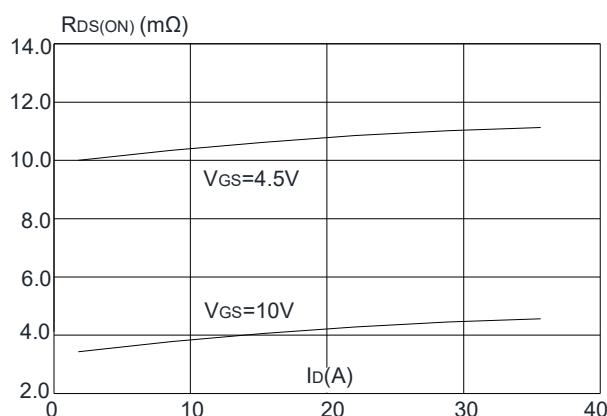
**Typical Characteristics:** ( $T_C=25^\circ\text{C}$  unless otherwise noted)



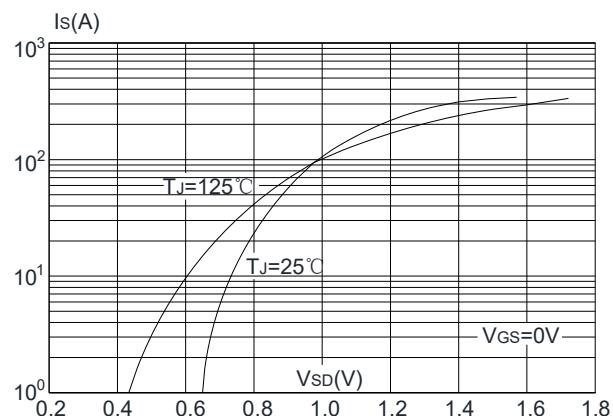
**Figure 1:** Output Characteristics



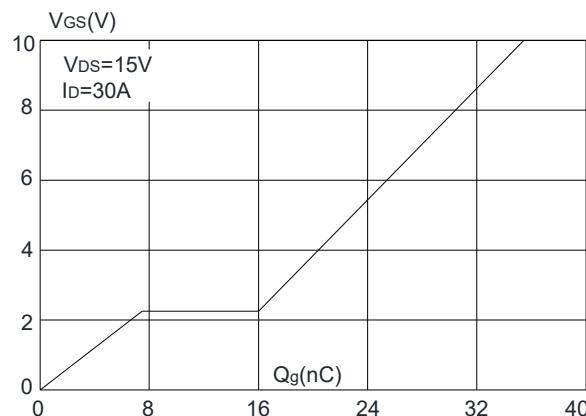
**Figure 2:** Typical Transfer Characteristics



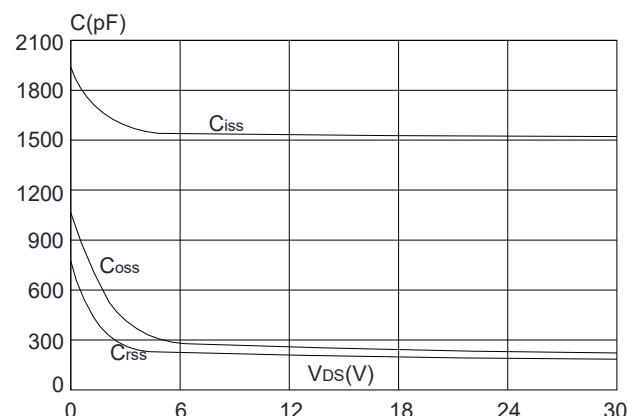
**Figure 3:** On-resistance vs. Drain Current



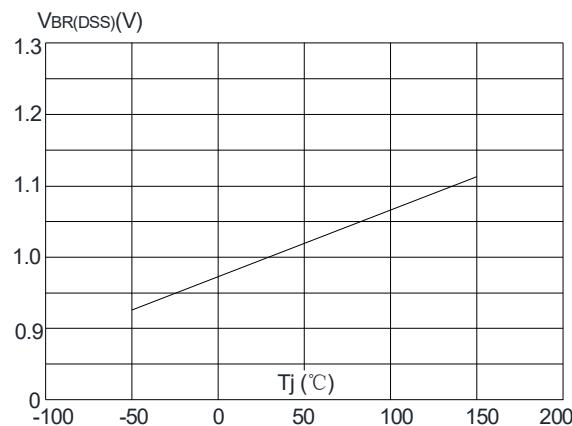
**Figure 4:** Body Diode Characteristics



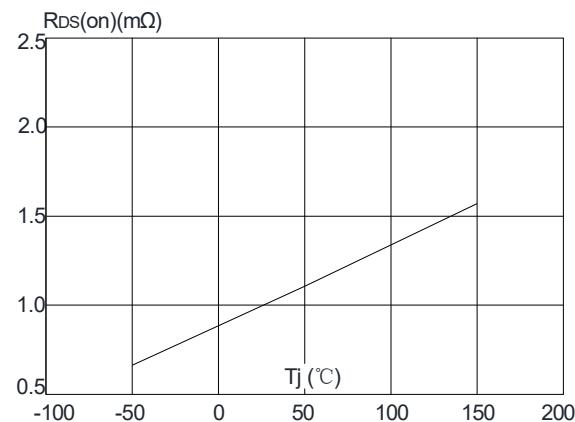
**Figure 5:** Gate Charge Characteristics



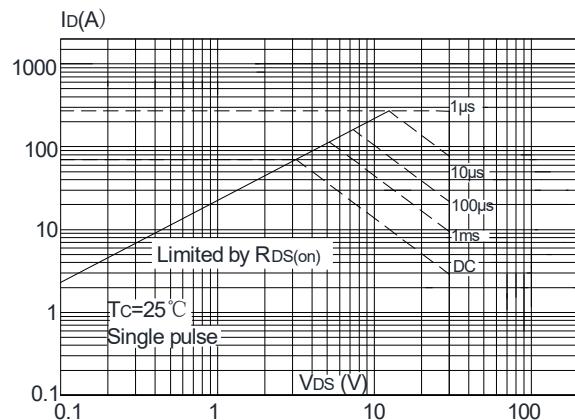
**Figure 6:** Capacitance Characteristics



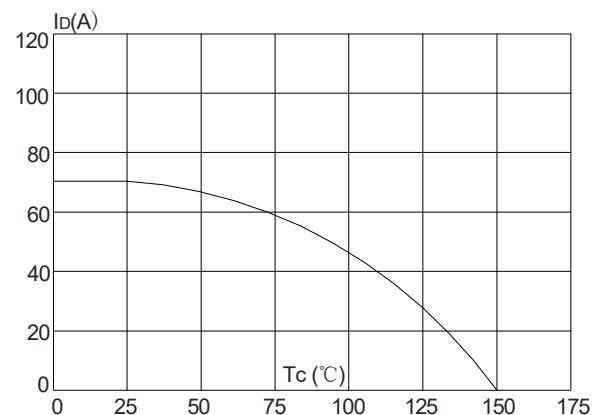
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



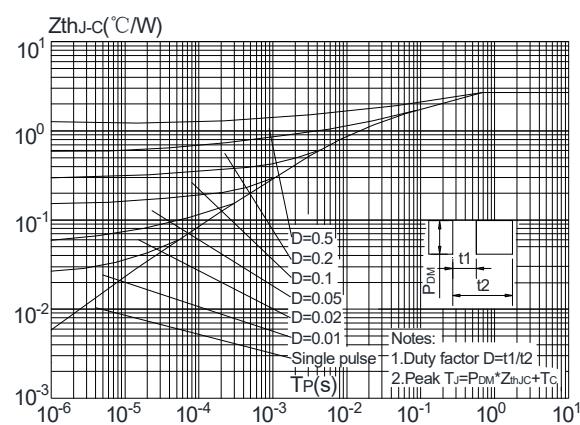
**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



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